DATA SHEET



PHOTOCOUPLER

PS2502-1,-2,-4,PS2502L-1,-2,-4

HIGH ISOLATION VOLTAGE DARLINGTON TRANSISTOR TYPE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

DESCRIPTION

The PS2502-1, -2, -4 and PS2502L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon darlington connected phototransistor.

The PS2502-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2502L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

- High isolation voltage (BV = 5 000 Vr.m.s.)
- High current transfer ratio (CTR = 2 000 % TYP.)
- High-speed switching (t_r, t_f = 100 μ s TYP.)
- Ordering number of tape product: PS2502L-1-E3, E4, F3, F4, PS2502L-2-E3, E4
- Safety standards
 - UL approved: File No. E72422 (S)

APPLICATIONS

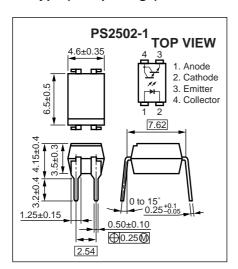
- Power supply
- Telephone/FAX
- FA/OA equipment
- · Programmable logic controller

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

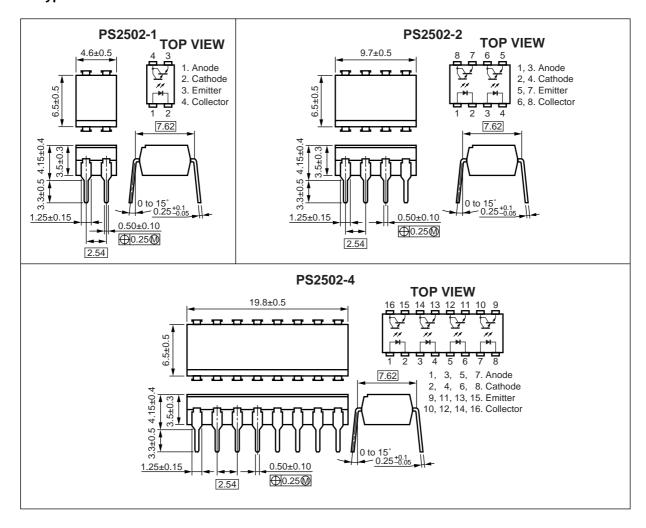
★ PACKAGE DIMENSIONS (UNIT: mm)

DIP Type (New package)

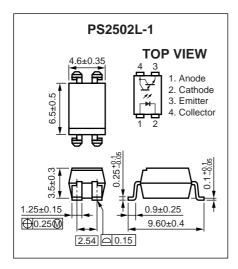


Caution New package 1-ch only

DIP Type

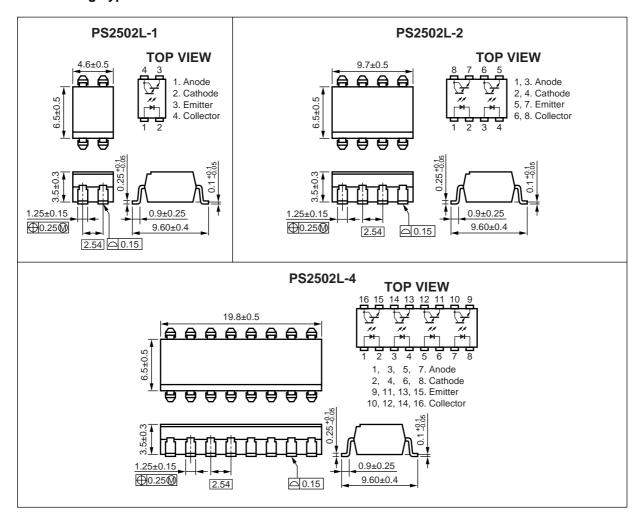


Lead Bending Type (New package)

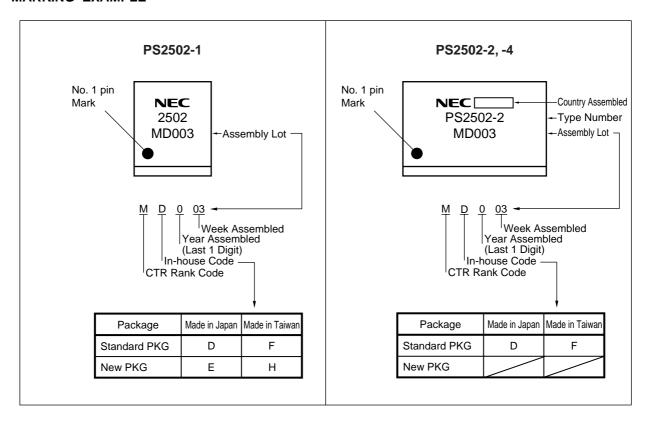


Caution New package 1-ch only

Lead Bending Type



★ MARKING EXAMPLE





ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ⁴
PS2502-1	4-pin DIP	Magazine case 100 pcs	PS2502-1
PS2502L-1			
PS2502L-1-E3		Embossed Tape 1 000 pcs/reel	
PS2502L-1-E4			
PS2502L-1-F3		Embossed Tape 2 000 pcs/reel	
PS2502L-1-F4			
PS2502-2	8-pin DIP	Magazine case 45 pcs	PS2502-2
PS2502L-2			
PS2502L-2-E3		Embossed Tape 1 000 pcs/reel	
PS2502L-2-E4			
PS2502-4	16-pin DIP	Magazine case 20 pcs	PS2502-4
PS2502L-4			

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2502-1, PS2502L-1	PS2502-2,-4 PS2502L-2,-4	
Diode	Reverse Voltage	VR	6		V
	Forward Current (DC)	lF	80		mA
	Power Dissipation Derating	∆P _D /°C	1.5	1.2	mW/°C
	Power Dissipation	Po	150	120	mW/ch
	Peak Forward Current ¹¹	IFP	1		Α
Transistor	Collector to Emitter Voltage	Vceo	40		V
	Emitter to Collector Voltage	VECO	6		V
	Collector Current	lc	200	160	mA/ch
	Power Dissipation Derating	∆Pc/°C	2.0	1.6	mW/°C
	Power Dissipation	Pc	200	160	mW/ch
Isolation Voltage ^{*2}		BV	5 000		Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

^{*1} PW = 100 μ s, Duty Cycle = 1 %

^{*2} AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

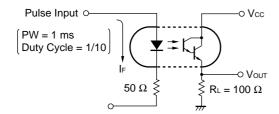
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.17	1.4	V
	Reverse Current	I R	VR = 5 V			5	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	ICEO	VcE = 40 V, IF = 0 mA			400	nA
Coupled	Current Transfer Ratio	CTR	IF = 1 mA, VcE = 2 V	200	2 000		%
	Collector Saturation Voltage	VCE(sat)	IF = 1 mA, Ic = 2 mA			1.0	V
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ¹¹			Ω
	Isolation Capacitance	Cı-o	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{'2}	tr	$Vcc = 10 \text{ V}, \text{ Ic} = 2 \text{ mA}, \text{ RL} = 100 \Omega$		100		μs
	Fall Time ^{*2}	tr			100		

*1 CTR rank (only PS2502-1, PS2502L-1)

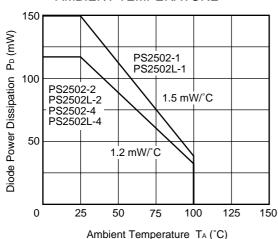
K : 2 000 to (%) L : 700 to 3 400 (%) M : 200 to 1 000 (%)

*2 Test circuit for switching time

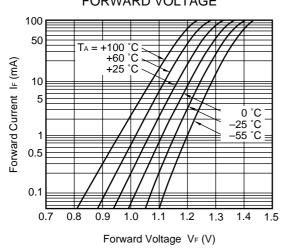


TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

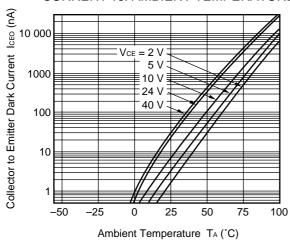




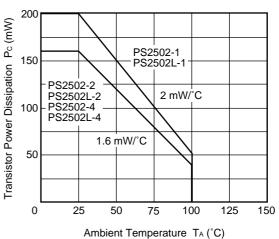
FORWARD CURRENT vs. FORWARD VOLTAGE



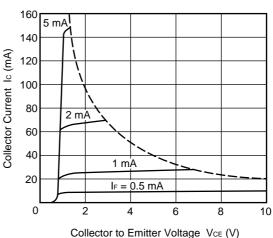
COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE



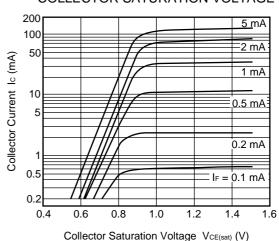
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



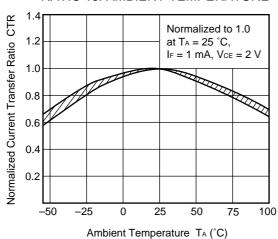
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



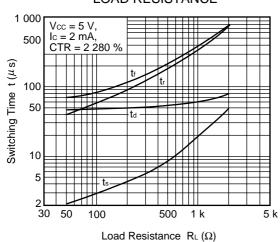
COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE



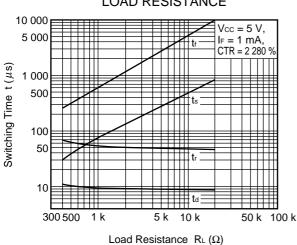
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



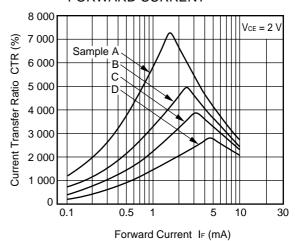
SWITCHING TIME vs. LOAD RESISTANCE



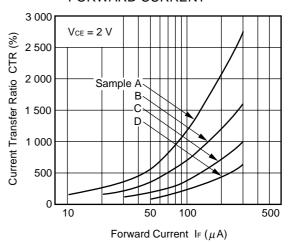
SWITCHING TIME vs. LOAD RESISTANCE



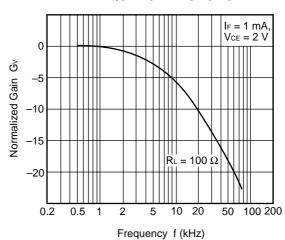
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



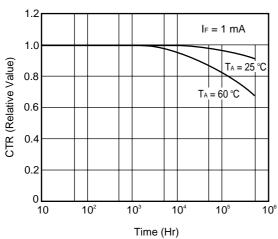
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



FREQUENCY RESPONSE

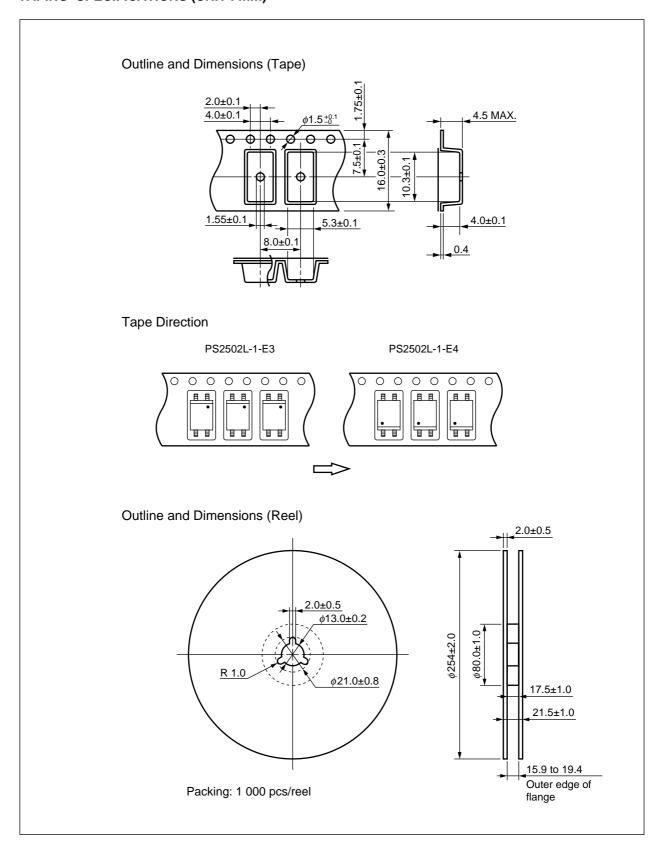


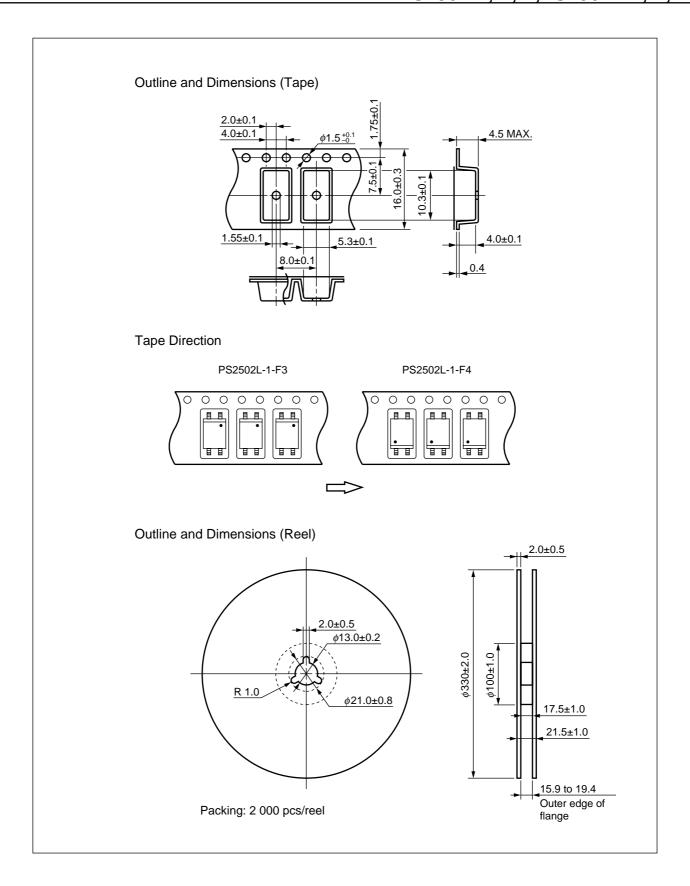
LONG TERM CTR DEGRADATION

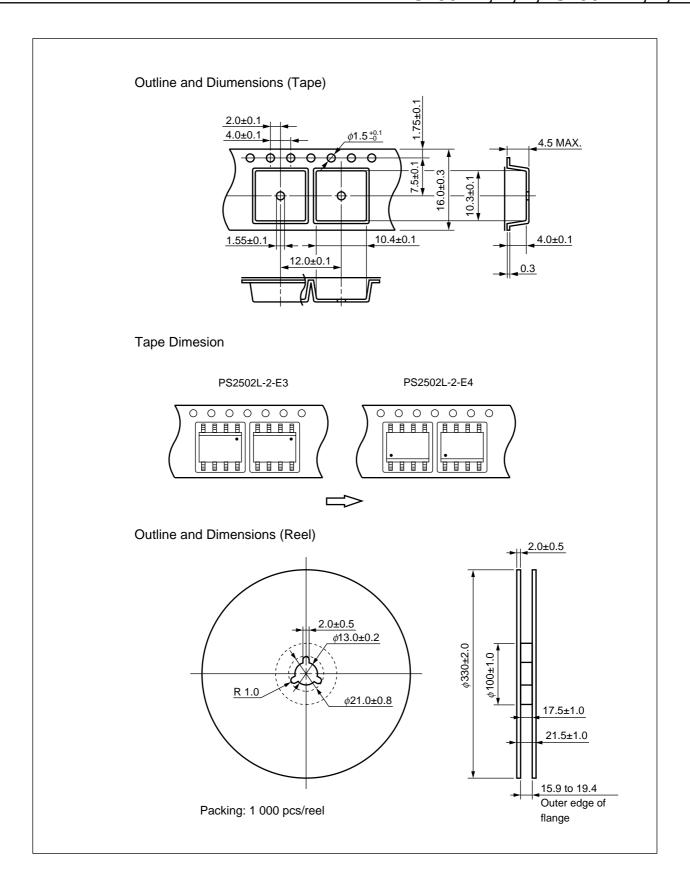


Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (UNIT: mm)







NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

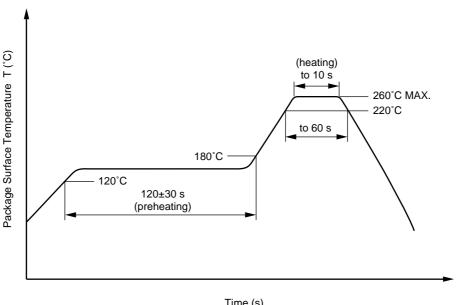
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

· Number of times One (Allowed to be dipped in solder including plastic mold portion.)

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine • Flux

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

★ USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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SAFETY INFORMATION ON THIS PRODUCT

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GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

▶ For further information, please contact

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